GSA

2025 INTERNATIONAL SUMMIT SHANGHAI

NOVEMBER 18

VeriSilicon 芯原

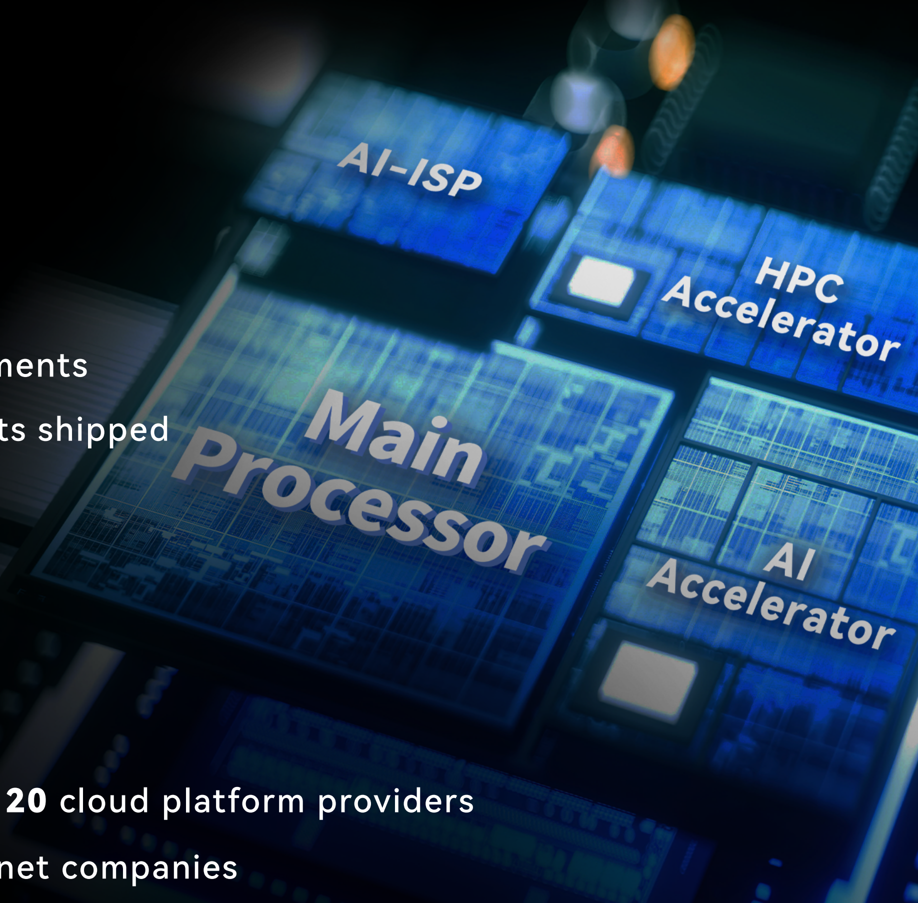
芯片设计平台即服务
Silicon Platform as a Service (SiPaaS®)

GPU IP

- **20** years of history
- **Over 2 billion** units shipped

High-End Intelligent Driving Chiplet

- **7/5nm** automotive-grade
- **300-500 TOPS** NPU
- **20+** CPU cores @ **2.3GHz** of each



NPU IP

- **91** customers
- **140+** SoCs
- **10+** application segments
- **Nearly 2 million** units shipped

VPU IP

- **12** of the world's **Top 20** cloud platform providers
- **3** of China **Top 5** internet companies
- **5** of China **Top 8** new EV makers

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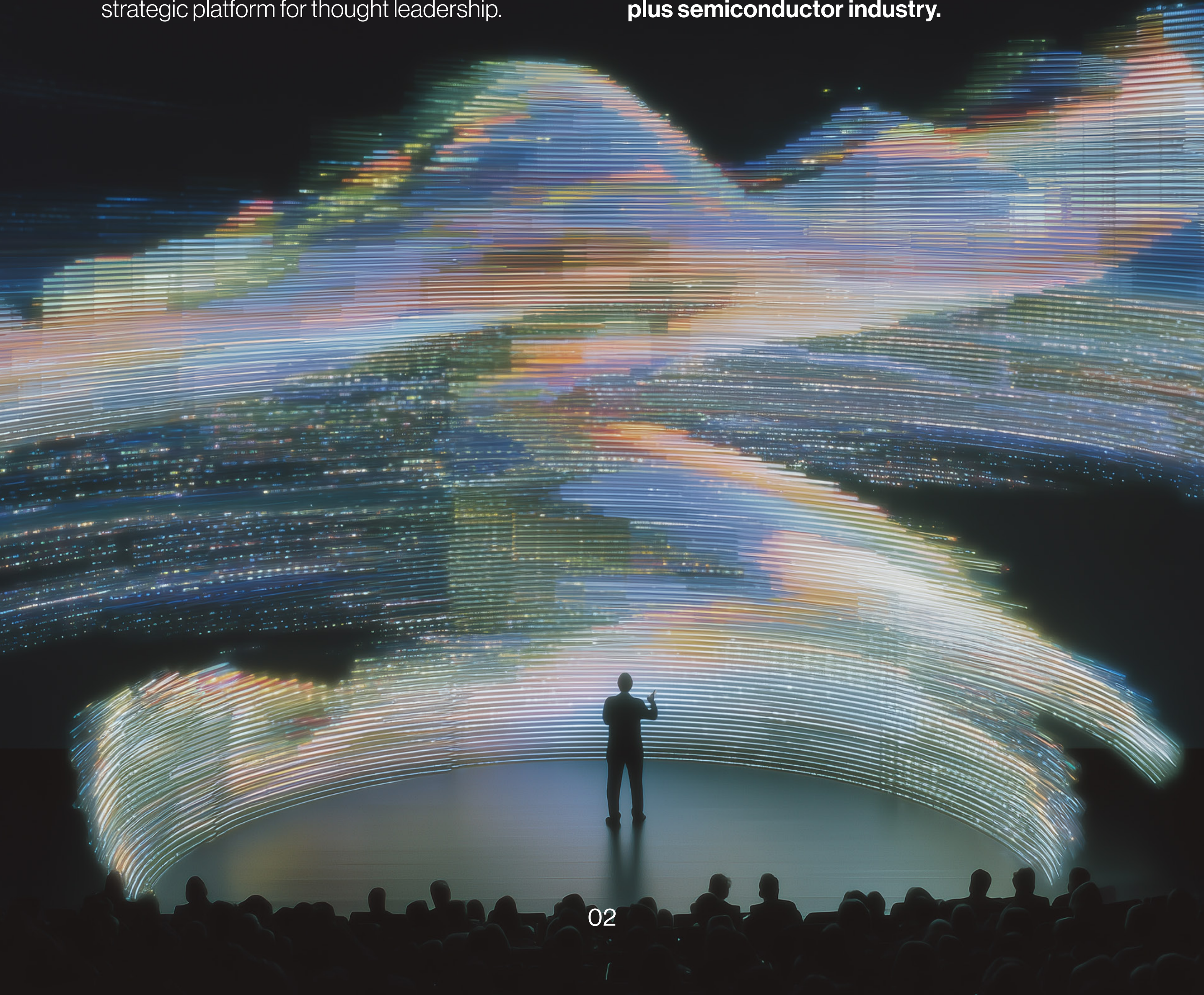
ABOUT GSA

WHERE LEADERS MEET

GSA is Where Leaders Meet to establish a profitable and sustainable semiconductor ecosystem. This expanding ecosystem encompasses semiconductors, software, solutions, systems and services. As a leading semiconductor and technology industry organization, we offer an efficient and strategic platform for thought leadership.

GSA has an impressive global footprint **representing 300+ corporate members** on six continents. As a result of our unique, neutral platform, our membership ranges from the most exciting, emerging companies to semiconductor industry stalwarts and technology leaders. Our members now represent **84% of the $662B plus semiconductor industry.**



WELCOME TO THE 2025 GSA INTERNATIONAL SUMMIT

On behalf of the **Global Semiconductor Alliance,** I am pleased to welcome you to the GSA International Semiconductor Summit.

This event brings together global leaders and innovators from across the semiconductor ecosystem to exchange insights, tackle shared challenges, and shape the strategies that will define the decade ahead.

As the semiconductor industry stands at the intersection of rapid innovation and shifting global markets, this year's program will explore the technologies and trends driving the next era of growth. Sessions will delve into **AI-driven innovation, automotive transformation**, and **breakthroughs in memory technology** that are enabling the next generation of computing. We will also examine critical issues such as supply chain resilience and the opportunities and challenges of integrating China's semiconductor industry more deeply into the global ecosystem.

We are honored to have an exceptional lineup of speakers who bring diverse perspectives and expertise to the table. I encourage you to make the most of this gathering, take the time to connect, exchange ideas, and collaborate with peers from around the world. Together, we can forge the path ahead and drive innovation that will lead us through both challenges and opportunities.

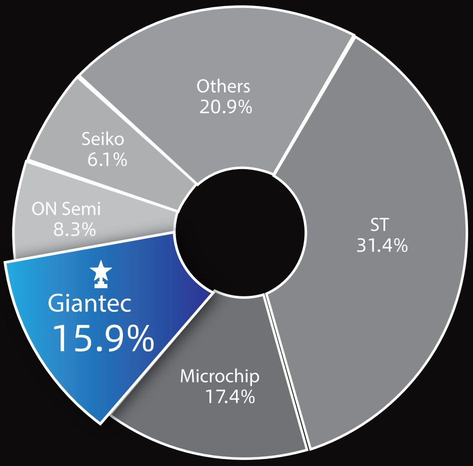
I would like to extend my sincere gratitude to our sponsors, VeriSilicon, Giantec, TSMC and SMIC, for their generous support in making this event possible. Their partnership reflects the spirit of collaboration and innovation that continues to drive our industry forward.

Thank you for being part of this year's **GSA International Summit**. I look forward to the discussions, connections, and ideas that will emerge as we collectively shape the future of semiconductors.

Jodi Shelton
Co-Founder & CEO
GSA

GIANTEC

Ranked Top 3 at Worldwide EEPROM Market



Unit: Million dollars

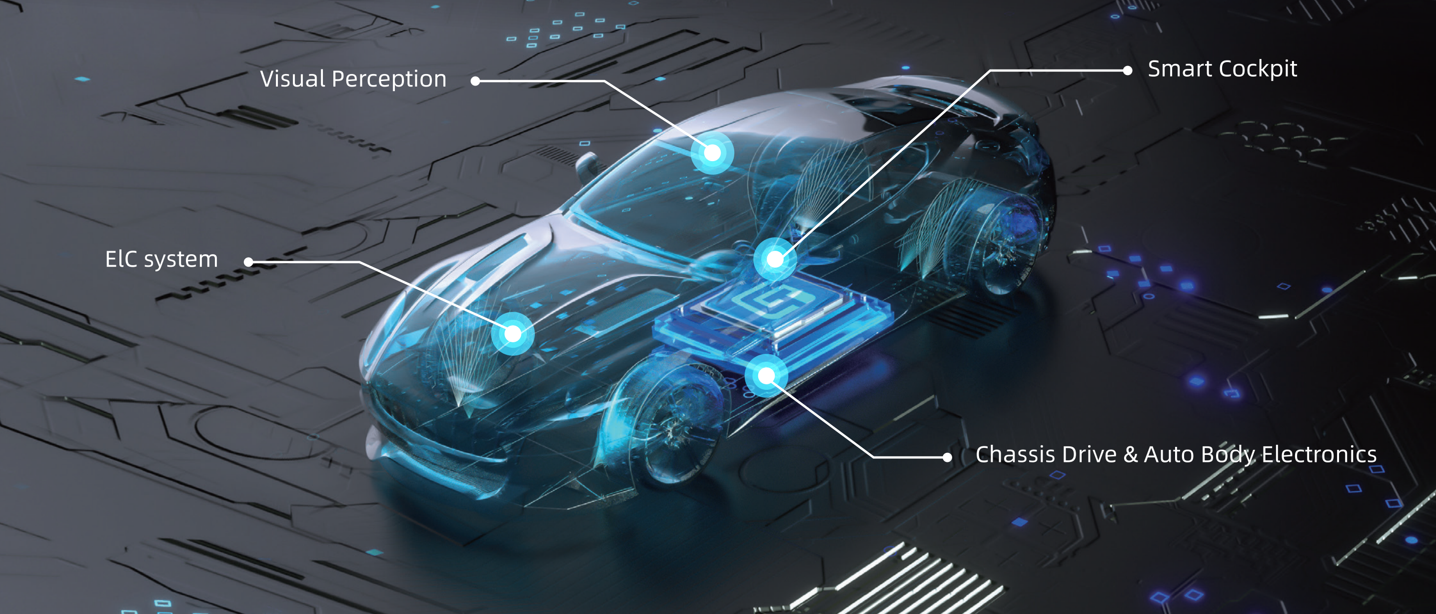
Ranking	Supplier	Sales in 2024
1	ST	249
2	Microchip	138
3	Giantec	126
4	ON	66
5	Ablic(Seiko)	48
6	Others	166
Sum		793

Source: Web-feet Research (Apr,2025)

Leadship in Automotive Memories

Our products

- Cover automotive 125°C and 105°C EEPROM and NOR Flash
- Reach core automotive applications, fully introduced with leading car manufacturers
- Achieved AEC-Q100 Grade 1 Automotive Qualification Standard
- Received Declaration of Conformity for the IATF 16949:2016(Compliance)



PROGRAM

13:00	**Registration**
13:30	**Welcome Remarks** · Jodi Shelton / CEO / GSA · Nicky Lu / Chairman of APAC Leadership Council & BOD Member / GSA; Chairman, Founder and CEO / Etron Technology · Haijun Zhao / BOD Member / GSA ; Co-Chief Executive Officer / SMIC
13:55	**Perspective on AI Activities in Edge and Data Centers** · Handel Jones / Founder and CEO / International Business Strategies (IBS)
14:30	**Making AI at the Tiny Edge A Reality and Why Ecosystem Matters** · Remi El-Ouazzane / President, Microcontrollers, Digital ICs and RF Products Group / STMicroelectronics
14:50	**Chiplet-Based High-End Intelligent Driving IC Design Platform** · Wayne Dai / Chairman, President and CEO / VeriSilicon
15:10	**Networking Break**
15:35	**High-Speed Connectivity Driving AI Systems** · Bill Brennan / President and CEO / Credo
15:55	**From Chips to Intelligence: AWS Fueling the AI Landscape** · Joey Zhu / General Manager of Industry Solutions in Greater China Region / Amazon
16:15	**Automotive Semiconductor Strategies Are Differentiating Chinese OEMs from Their Global Peers** · Yu Yang / Principal Analyst, Automotive Semiconductors / Yole Group
16:35	**Panel Session - How Chinese Players Going Abroad Are Reshaping the Global Automotive Semiconductor Landscape** Moderator: · Yu Yang / Principal Analyst, Automotive Semiconductors / Yole Group Panelists: · Hongyu Wang / Regional President Asia-Pacific, Regional President / Bosch Sensortec GmbH, Bosch Semiconductors China · Henry Cao / Executive Vice President, Sales & Marketing, China Region / STMicroelectronics · Xiaoxin Qiu / Founder & Chairman / Axera Semiconductor Co., Ltd. · Wilson Ni / General Manager & Chief Revenue Officer, Elektrobit China / Elektrobit
17:05	**Closing Remarks**
17:10	**VIP Reception / VIP Dinner**

INTEGRITY · COMMITMENT · INNOVATION · CUSTOMER TRUST

TSMC Core Values

Integrity

Integrity is our most basic and most important core value. We tell the truth. We do not make commitments lightly. Once we make a commitment, we devote ourselves completely to meeting that commitment.

Commitment

TSMC is committed to the welfare of customers, suppliers, employees, shareholders, and society.

Innovation

Innovation is the wellspring of TSMC's growth, and is a part of all aspects of our business, from strategic planning, marketing and management, to technology and manufacturing.

Customer Trust

At TSMC, customers come first. Their success is our success, and we value their ability to compete as we value our own. We strive to build deep and enduring relationships with our customers, who trust and rely on us to be part of their success over the long term.

BILL BRENNAN

President and CEO

CREDO

For more than 25 years, Bill Brennan has been leading and scaling organizations to deliver steady revenue growth and profit. Bill joined Credo in 2013, leading the company to its IPO in January 2022. He has overseen Credo's growth from a small startup to an organization of more than 500 employees worldwide. Under his stewardship, the company has pioneered revolutionary networking technologies based on Credo's high-performance, low-power SerDes technology, including Active Electrical Cables (AECs) and Linear Receive Optics (LRO). Bill also supports numerous national and regional nonprofit organizations focused on health, education, and children's causes.

Before joining Credo, Bill served as Vice President of the Storage Business Unit with Marvell Semiconductor for 11 years. Prior to Marvell, he held sales management positions with NEC and Texas Instruments. Bill received his BSEE degree from the University of Colorado.

HANDEL JONES

Founder and CEO

International Business Strategies (IBS)

Dr. Jones has over 50 years of experience in the electronics industry. He held senior management positions at ITT and other companies. At Rockwell, he was VP of Strategic Planning, Acquisitions, International Marketing, and Engineering of the Commercial Electronics Group. As VP of Engineering at Rockwell, Dr. Jones had over 1,500 engineers reporting to him, covering communications, avionics, and semiconductors. Dr. Jones was also the President and COO of a publicly traded semiconductor company. He steered the company through a successful public offering and a key acquisition.

Dr. Jones has written various books on China, including When AI Rules the World, Artificial Intelligence: How AI and IA Reshape the Future, China's Globalization (How China Becomes No. 1), and Chinamerica (McGraw-Hill).

HENRY CAO

Executive Vice President, Sales & Marketing, China Region

STMicroelectronics

Henry Cao is Executive Vice President of Sales & Marketing for STMicroelectronics' China Region, where he oversees the company's business strategy, operations, key account development, and new growth initiatives in China. With more than 30 years of management experience in the technology industry, he brings deep expertise in automotive electronics, data center, telecom and consumer electronics. Prior to joining ST, he held key leadership roles at multinational corporations such as Siemens Communications and Dell, and has a strong track record in product management, business development, ecosystem building and strategic operations.

Since joining STMicroelectronics in 2020, he has led the acceleration of the company's localization efforts in China. Under his leadership, ST has successfully launched a silicon carbide joint venture with Sanan Optoelectronics in Chongqing, strengthened wafer manufacturing collaboration with HHGrace Semiconductor, and built a close local partner ecosystem. He has been instrumental in deepening the integration of ST's technology into applications for key industries in China, driving robust business growth.

HONGYU WANG

Regional President Asia-Pacific ,
Regional President

Bosch Sensortec GmbH, Bosch Semiconductors China

Mr. Hongyu Wang is Bosch Sensortec Regional President Asia-Pacific and Bosch Semiconductor Regional President China. With nearly 18 years of experience in the sensor and semiconductor industry, he joined Bosch in 2006 and has since held various roles across multiple divisions and regions.

Mr. Wang began his career at Bosch Corporate Research in Stuttgart, focusing on hardware and algorithm development for sensor-related digital signal processing. In 2009, he moved to Bosch Automotive Electronics (Suzhou) as the Manager of Electronic System Development, and in 2010, joined Bosch Sensortec (Shanghai) as an ASIC Project Manager and Department Head. He later transitioned to BSH Home Appliances (Nanjing) in 2018, overseeing electronic systems and software development, and was appointed Head of the Global Electronics and Motor Division (Greater China) in late 2019.

He holds a Bachelor's degree in Electrical Engineering from Zhejiang University and a Master's degree in Electrical Information Technology from the University of Stuttgart.

JOEY ZHU

General Manager of Industry Solutions in Greater China Region

Amazon

Joey Zhu serves as the General Manager of Industry Value Transformation for AWS Greater China Region, where he specializes in driving clients' digital transformation through cloud-native and AI-powered industry solutions.

With nearly three decades of IT consulting experience spanning both Chinese and international markets, Joey brings deep expertise in digital strategy, IT operating models, large-scale transformation programs, and complex project management. His extensive background covers multiple sectors, including manufacturing, telecommunications, and high-tech industries.

Before joining AWS in 2022, Joey was a Partner at IBM Consulting (GBS), where he led several key service lines including Hybrid Cloud Transformation, Cognitive Business Decision Support (Data Strategy and Implementation), and Corporate Operation Strategy. He holds a Master's degree from the University of Sydney.

REMI EL-OUAZZANE

President, Microcontrollers, Digital ICs and RF Products Group

STMicroelectronics

Remi El-Ouazzane is STMicroelectronics' President, Microcontrollers, Digital ICs and RF Products Group and has held this position since February 2024. He is also functionally responsible for the corporate System Research and Applications organization and is a member of ST's Executive Committee.
El-Ouazzane started his career at Texas Instruments in 1997. He rose through the ranks across the broadband, mobile, and embedded processing divisions to become Vice President and General Manager of the Open Multimedia Applications Platform (OMAP) in 2009. El-Ouazzane was appointed CEO of Movidius in 2013, responsible for driving its vision-processing technologies to advance the adoption of AI in the Internet of Things. With the acquisition of Movidius by Intel in 2016, he joined Intel's New Technology Group as Vice President and General Manager, and became Chief Operating Officer of Intel's Artificial Intelligence Products Group in 2018. In 2020, El-Ouazzane became Intel's Datacenter Platform Group Chief Strategy Officer, driving strategic initiatives in the data center and cloud markets.
In 2009, El-Ouazzane was honored with the French-American Foundation's Young Leaders Award.
Remi El-Ouazzane was born in Neuilly-sur-Seine, France in 1973 and graduated from the Grenoble Institute of Technology (INPG) in 1996 and the Grenoble Institute of Political Studies in 1997. He graduated from the General Management Program at Harvard Business School in 2004.

WAYNE DAI

Chairman, President and CEO

VeriSilicon

Dr. Wayne Dai founded VeriSilicon in August 2001 and has served as the chairman of the board of directors, President and Chief Executive Officer since then. Prior to founding VeriSilicon, Dr. Dai was the Co-Chairman and Chief Technology Officer of Celestry Technologies, Inc., an EDA company, which was acquired by Cadence Design Systems in 2002. Prior to that, he was the founder, chairman of the board of directors, and Chief Executive Officer of Ultima Interconnect Technology, Inc., one of the predecessor companies to Celestry.

Dr. Dai was the founding Chairman of the IEEE Multi-Chip Module Conference and IEEE Symposium on IC/Package Design Integration, Co-Chairman of the Program Committee of the 2010 International Green Energy Forum. He was an Associate Editor of IEEE Transactions on Circuits and Systems and an Associate Editor of IEEE Transactions on VLSI Systems. He has published more than 100 papers in technical journals and conferences and received the NSF Presidential Young Investigator Award from the President of United States in 1990. He was recognized as top ten venture-backed entrepreneurs and top ten talents of science and technology in China in 2005. He was honored with The Ernst & Young Entrepreneur of the Year in China in 2007. He won the ACE's Executive of the Year award in 2013, the Hurun Industry Achievement Award in 2014, the APAC Innovator of the year of WEAA in 2018, and was recognized as a "Leading Pioneer" in 2018 by Shanghai Smart City Construction, 2019 Contributor of the year and 2021 Outstanding Contributor of Industry Progress of WEAA, the 2021 Sci-Tech Innovation Golden Horse Awards Outstanding Leader award, 2023 Annual Outstanding Person of China IC Industry, and High Tech Contributor of the Year of 2023 Compass Tech Award. He is currently the Vice Chairman of Global Innovation Center, the Executive Vice President of the International Union for Science and Technology Innovation, the Vice President of the China Semiconductor Industry Association IC Design Branch, the President of the China RISC-V Industry Consortium, the Vice President and the Expert Committee Member of the Automotive Electronics Industry Alliance, the President of the Shanghai Open Processor Innovation Center, the Vice President of Shanghai Integrated Circuit Industry Association, the Vice Chairman of the Expert Committee of the Shanghai IC Industry Cluster Development Promotion Institution, and the President of Berkeley Club of Shanghai.

Dr. Dai received his B.A. degree in Computer Science and his Ph.D. degree in Electrical Engineering from the University of California at Berkeley. He was a professor in the department of Computer Engineering at the University of California at Santa Cruz.

WILSON NI

General Manager & Chief Revenue Officer, Elektrobit China

Elektrobit

Wilson Ni is CRO & GM for region China at Elektrobit, an award-winning and visionary global vendor of embedded and connected software products and services for the automotive industry.

Prior to that, Wilson served over 14 years at Continental as head of segment APAC for body electronics covering China/Japan/Korea and South East Asia markets.

Wilson studied in Shanghai Jiaotong University from 2000-2004 with a bechlor degree major in automotive engineering.

XIAOXIN QIU

Founder & Chairman

Axera Semiconductor Co., Ltd.

Dr. Xiaoxin Qiu, Founder and Chairman of Axera Semiconductor Co., Ltd., has been employed in the semiconductor industry for more than 20 years. She was the CTO of UniSoC Corp,responsible for defining the company technology and product roadmaps, and leading the R&D effort. Before joining UniSoC Corp, as the Vice President of Broadcom Corporation, she was deeply involved in the development of the mobile communication chips and products, and led a large international R&D team, directly serving tier 1 customers such as Samsung, Nokia, and Ericsson. Before Broadcom, Xiaoxin Qiu was the Principal Scientist at AT&T labs – Research, conducting researches on wireless communications systems.

Dr. Xiaoxin Qiu has a Bachelor's and Master's degree in Automation from Tsinghua University and a Doctor's degree in Electrical Engineering from the University of Southern California.

YU YANG

Principal Analyst, Automotive Semiconductors

Yole Group

Yu Yang, PhD is Principal Analyst, responsible for Automotive Semiconductors at Yole Group.

Based in Belgium, he is engaged in the development of technology and market products, especially automotive industry. Yu is deeply engaged in coordinating all studies and activities within the automotive industry.

Yu Yang has authored numerous analyses for Yole Group, including Automotive Powertrain and Electrification 2025, Vol. 1, Automotive 48V Powernet, Power Electronics for xEV, and Semiconductor Trends in Automotive, among others.

He actively participates in international automotive trade shows and conferences, where he regularly presents Yole Group's insights and vision on the evolving dynamics of the automotive sector.

Prior to Yole Group, Yu worked as a business development partner and R&D project leader at Punch Powertrain N.V. (Belgium), R&D project manager at Bekaert N.V. (Belgium), and doctorate researcher at IMEC (Belgium).

Yu Yang holds a PhD in materials engineering from Leuven University (Katholieke Universiteit Leuven) in Belgium and a master's in electrical engineering from Tsinghua University (China).

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VeriSilicon

Under the its unique “Silicon Platform as a Service” (SiPaaS) business model, VeriSilicon is committed to providing customers with platform-based, all-around, one-stop custom silicon services and semiconductor IP licensing services leveraging its in-house semiconductor IP. For more information, please visit: www.verisilicon.com.

VIP RECEPTION SPONSOR

GIANTEC

Founded in 2009, Giantec specializes in the design of memory, analog, and mixed-signal integrated circuits. Its extensive product portfolio includes memories (EEPROM & NOR Flash), VCM Driver ICs, and Smart Card ICs, serving diverse industries such as automotive electronics, smartphones, DIMM, industrial control, LCD panels, and white goods. For more information, please visit: www.giantec-semi.com.

PLATINUM SPONSOR

TSMC created the semiconductor Dedicated IC Foundry business model when it was founded in 1987. In 2023, TSMC served 528 customers and manufactured 11,895 products for various applications covering a variety of end markets including high performance computing, smartphones, the Internet of Things (IoT), automotive, and digital consumer electronics. Annual capacity of the manufacturing facilities managed by TSMC and its subsidiaries exceeded 16 million 12-inch equivalent wafers in 2023.

GOLD SPONSOR

Semiconductor Manufacturing International Corporation (SMIC, 00981.HK/688981.SH) is one of the leading foundries in the world and is the front runner in manufacturing capability, manufacturing scale, and comprehensive service in the Chinese Mainland. SMIC Group provides semiconductor foundry and technology services to global customers on 8-inch and 12-inch wafers. Headquartered in Shanghai, China, SMIC Group has an international manufacturing and service base, with 8-inch and 12-inch wafer fabrication facilities in Shanghai, Beijing, Tianjin and Shenzhen. SMIC Group also has marketing and customer service offices in the U.S., Europe, Japan, and Taiwan, China.

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Thank you for attending GIS! Connet with us on our social media channels to stay current with industry news and GSA events.

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2025 AWARDS CELEBRATION

GSA

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